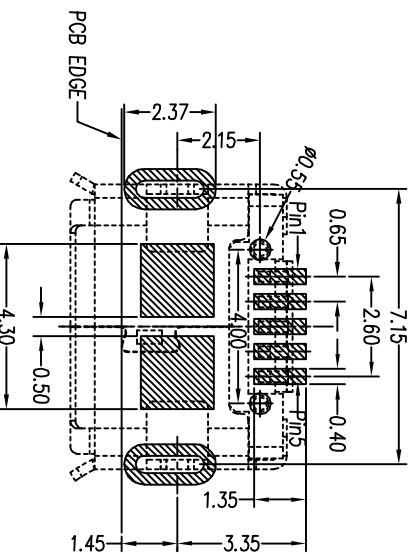
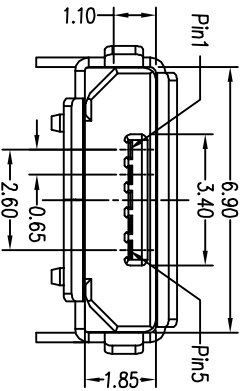
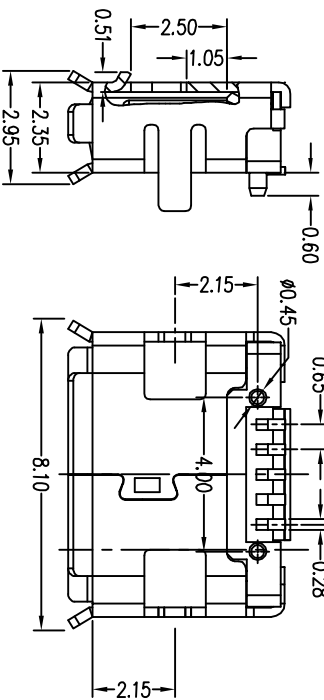
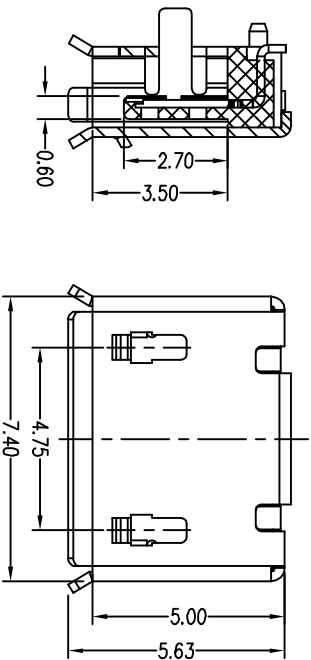
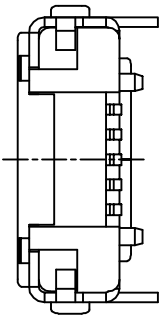


REV.	EQN NO	LOCATIONS	DESCRIPTION	DATE	REVISER	APPD



RECOMMENDED PCB LAYOUT

- Note:
- Material:
 - Housing: High temperature thermoplastic with g.f;UL94V-0
 - Contact: copper alloy,t=0.20mm
 - Shell: copper alloy,t=0.25mm
 - Specification:
 - Current rating: 1 A Max.
 - Dielectric withstanding voltage: 100 V(ac) for 1 min.
 - Contact resistance: 50 mΩ Max.
 - Insulation resistance: 100 MΩ Min.
 - Total mating force: 3.57 Kgf Max.
 - Total unmating force: 1.0 Kgf Min.0.81~2.05 Kgf Min.after 10000 insertion/extraction cycles
 - Temperature range:-30°C~80°C

Order Information:

1-MD05SMXXX-02
 ① ② ③ ④ ⑤ ⑥ ⑦ ⑧ ⑨

- | | | | |
|----------------|-----------|--------------------|------------------|
| 1: Assy. | 5: Style | 7: Contact plating | 8: Shell plating |
| 2: Series No. | M: Smt | 1: 1u" | T: Tin |
| 3: Contact No. | W: Black | 2: 3u" | N: Nickel |
| 4: P: Plug | N: White | 3: 5u" | A: Au plated all |
| 5: Socket | N: Nature | 4: 15u" | B: None |
| | | 5: 30u" | ... |

No.	Nome	Q'ty	Finish
3	Shell	1	N/A
2	Contact	5	N/A
1	Housing	1	N/A

PART NO: 1-MD05SMXXX-02	MATERIAL: SEE NOTE	TITLE: Micro usb 5s AB Type DIP7.2	
MODEL NO:	FINSH: SEE NOTE	DWG NO: SHK-20044	REV: A
UNIT: mm	SIZE: A4	APP: 1:1	SHEET: 2009/04/21
TOLERANCE UNSPECIFIED		SCALE: 1:1	
.x	±0.38	REV: A	
.xx	±0.25	REV: A	
.xxx	±0.13	REV: A	
ANG.	±2°	REV: A	

深圳市虹康科技有限公司

F

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